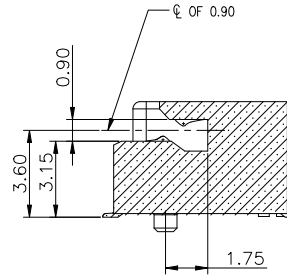
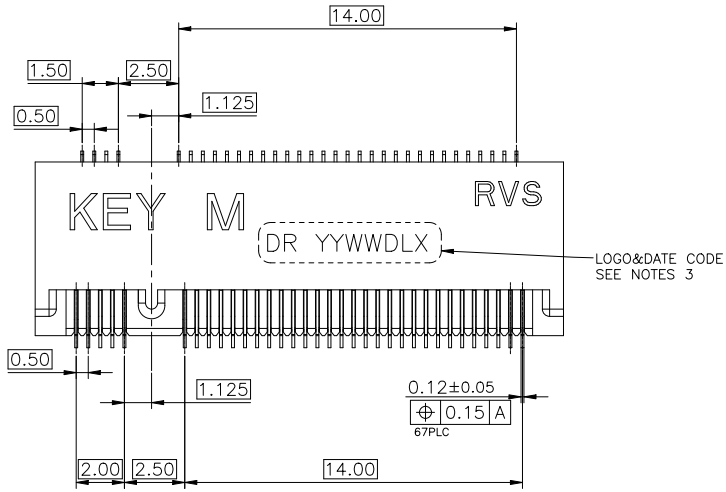
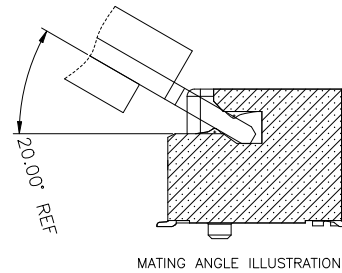
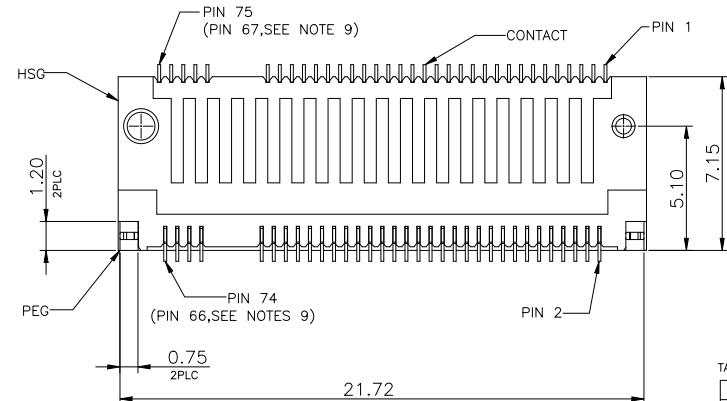
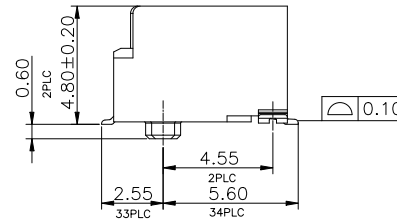
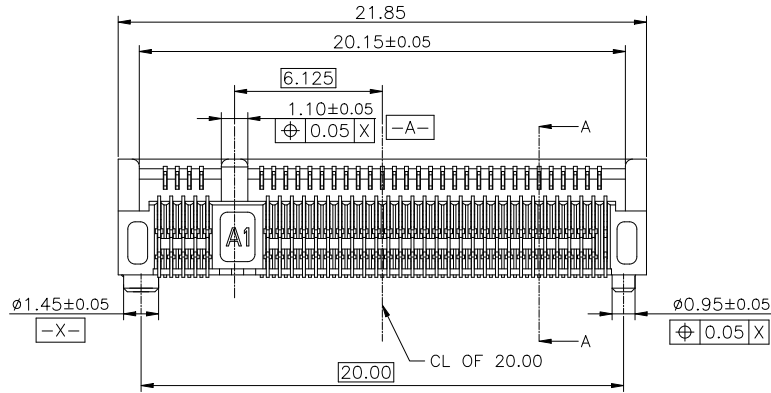


# HF

Halogen Free



SECTION A-A  
SCALE 1:1



MATING ANGLE ILLUSTRATION

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	2024.07.02	Sid Guo

- NOTES:  
 PRODUCT MUST MEETS CONTROLLED SUBSTANCES SPEC. ROHS 2.0 AND MEET DEREN CONTROLLED SUBSTANCES SPEC PER WI-PB-S-010
- 1.MATERIAL:  
 1.1 HOUSING:HIGH TEMPERATURE THERMOPLASTIC, UL94V.0; COLOR: BLACK  
 1.2 CONTACT:COPPERY ALLOY.  
 1.3 SOLDER PEG AND LATCH:STAINLESS STEEL.
- 2.FINISH:  
 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER. GOLD FLASH PLATING ON SOLDERTAIL. GOLD PLATING (SEE NOTE 10) ON CONTACT AREA.  
 2.2 SOLDER PEG:  
 MATTE TIN 100u" MIN. AND NICKEL 50u" MIN UNDERPLATED.
- 3.LOGO&DATE CODE:  
 LOGO: DR OR DEREN  
 DATECODE: YYWDLX  
 YY: YEAR (09: 2009)  
 WW: WEEK (25: THE 25TH WEEK)  
 D: DAY (1~7: SUNDAY~SATURDAY)  
 L: LINE NUMBER OF ASSEMBLY (A: LINE A)  
 X: MANUFACTURE CODE
- 4.REFLOW SOLDER CAPABLE TO 260°C 10 SEC.
- 5.ELECTRICAL CHARACTERISTICS :  
 5.1 CURRENT RATING:0.5AMP.  
 5.2 CONTACT RESISTANCE:55 MILLIOHMS MAX. INITIAL, 20 MILLIOHMS MAX. CHANGE AFTER TEST.  
 5.3 IMPEDANCE:85±10% OHMS  
 5.4 INSULATION RESISTANCE:500 MEGOHMS MIN. INITIAL 100 OHM MIN. CHANGE AFTER TEST.  
 5.5 DIELECTRICAL WITHSTAND VOLTAGE:300V AC MIN.AT SEA LEVEL.
- 6.MECHANICAL CHARACTERISTICS:  
 6.1 INSERTION FORCE:20N MAX.PER CONTACT PAIR.  
 6.2 DURABILITY:60 MATING AND UNMATING CYCLES.
- 7.ENVIRONMENTAL CHARACTERISTICS:  
 OPERATING TEMPERATURE RANGE:-40°C TO +80°C.
- 8.RECOMMENDED STENCIL THICKNESS:0.12MM MIN.
- 9.CONNECTOR ACTUAL PIN QUANTITY IS 67,AS THE KEY TAKING OUT 8 PINS.
- 10.PART NUMBER DESCRIPTION:  
 5621D3-002 H X B 1 1 2

- PACKING CODE:  
2: EMBOSS WIDTH 44mm, SLOT BACKWARD
- LOGO:  
0:NO LOGO  
1:DR LOGO
- Color:  
1:Black  
2:White
- KEY TYPE:  
B: KEY M
- PLATING CODE:  
1: Au GF 2: Au 5u"  
3: Au 10u" 4: Au 15u" 5: Au30u"
- HALOGEN CODE:  
H:HALOGEN FREE

TABLE 1:

PART NUMBER	DESCRIPTION	DIM	TOL	DIM	TOL
5621D3-002H1B112	Au G/F ON CONTACT AREA	.X	±0.30	.X	±2*
5621D3-002H2B112	Au 5u" ON CONTACT AREA	.X	±0.25	.X	±1*
5621D3-002H3B112	Au 10u" ON CONTACT AREA	.XX	±0.15		
5621D3-002H4B112	Au 15u" ON CONTACT AREA				
5621D3-002H5B112	Au 30u" ON CONTACT AREA				



**DEREN**  
 SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.  
 SC2007085-1

C-DWG:	TY	DATE
DESIGN:	Sid Guo	2024.07.02
CHECK:	Mike Chen	2024.07.02
APPROVAL:	Bill Lin	2024.07.02

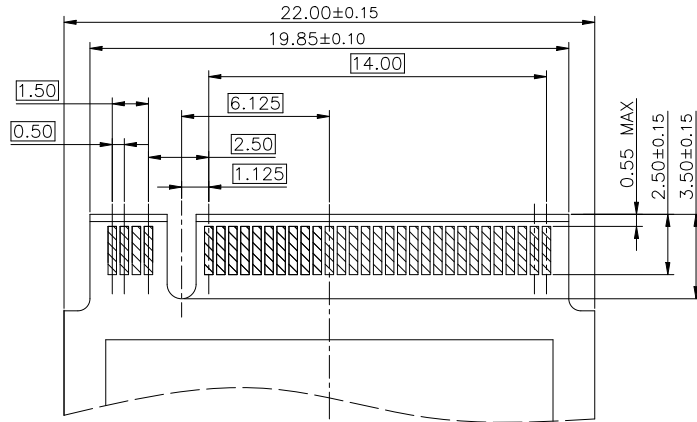
TITLE:NGFF 4.80H KEY M RVS GEN4	P/N: SEE TABLE 1
SHEET: 1/3	
SCALE: N/A	UNIT: mm

REV. A

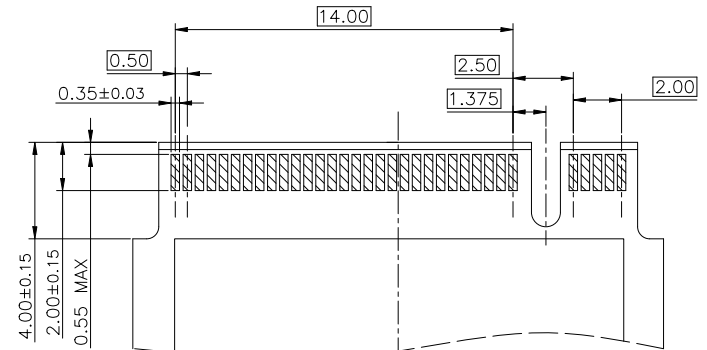
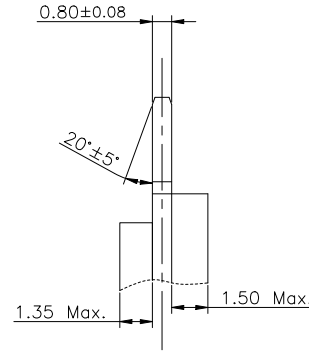
# HF

Halogen Free

## PLUG PCB

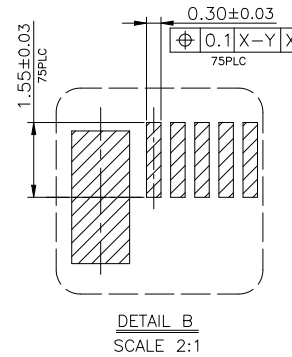
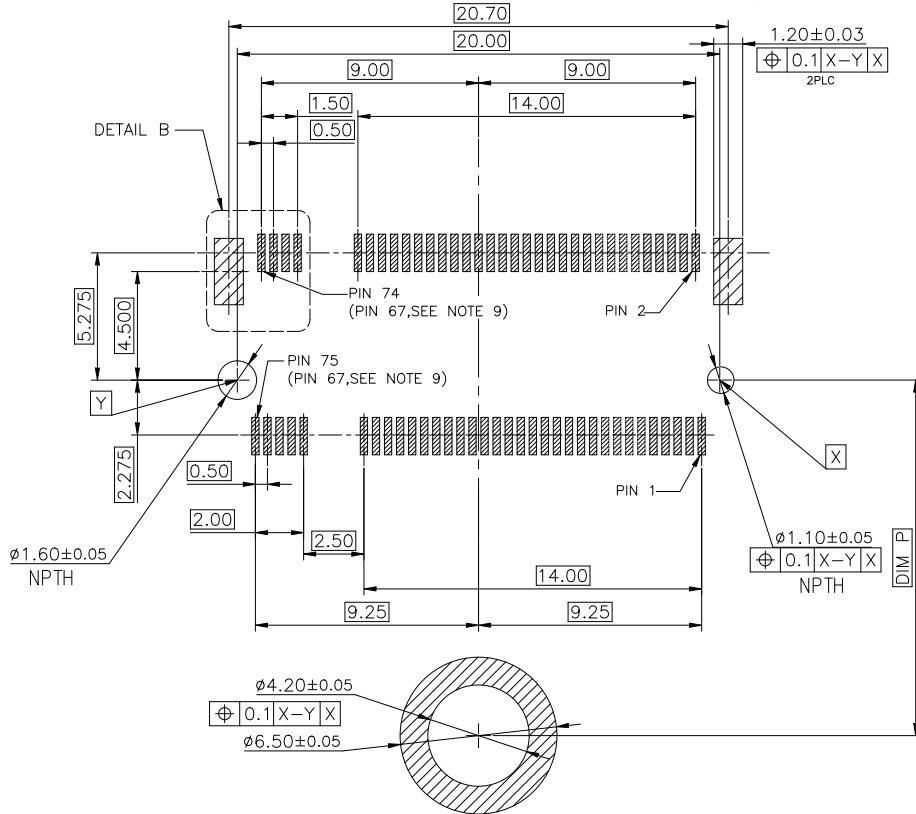


BOTTOM SIDE



TOP SIDE

### RECOMMENDED PCB LAYOUT(TOP VIEW)



22110	108.25
2280	78.25
2260	58.25
2242	40.25
2230	28.25
3042	40.25
3030	28.25
MODULE TYPE	DIM P

DIM	TOL	DIM	TOL
.x	±0.30	x	±2°
.x	±0.25	.x	±1°
.xx	±0.15		

**DEREN**  
SHENZHEN DEREN ELECTRONIC CO., LTD

C-DWG:	TY	DATE	TITLE:NGFF 4.80H KEY M RVS GEN4
DESIGN:	Sid Guo	2024.07.02	P/N: SEE TABLE 1
CHECK:	Mike Chen	2024.07.02	SHEET: 2/3
APPROVAL:	Bill Lin	2024.07.02	SCALE: N/A UNIT: mm

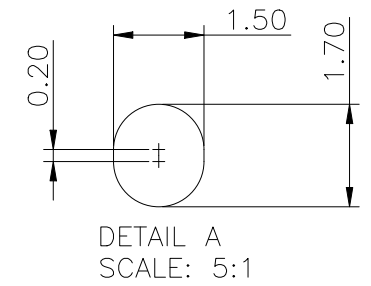
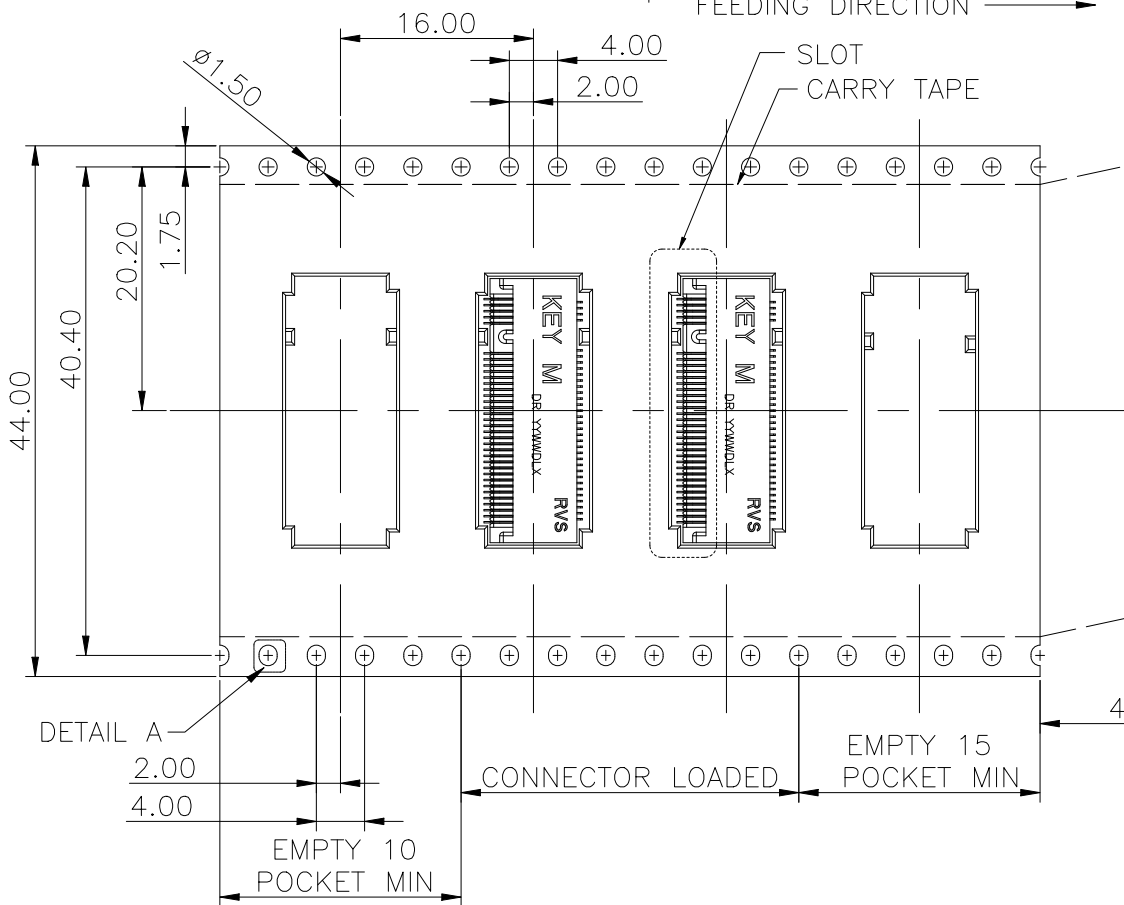
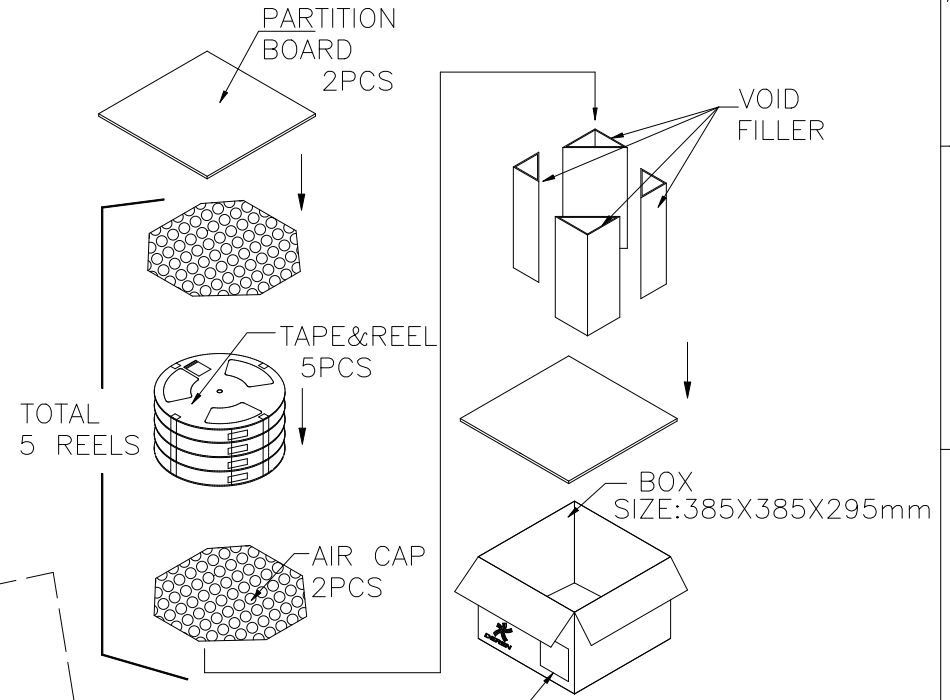
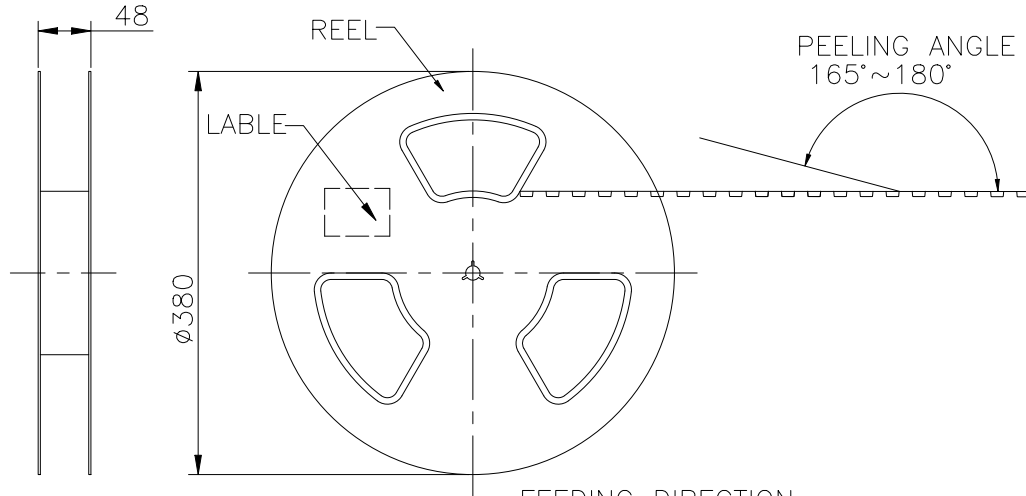
DRAW NO. SC2007085-1

REV. A

# HF

Halogen Free

### EMBOSS WIDTH 44mm, SLOT BACKWARD



900	5	4500
PCS/REEL	REELS/BOX	PCS/BOX

DIM	TOL	DIM	TOL
x.	±0.30	x.	±2'
.x	±0.20	.x	±1'
.xx	±0.15		

**DEREN**  
SHENZHEN DEREN ELECTRONIC CO., LTD

C-DWG:	TY	DATE	TITLE: NGFF 4.80H KEY M RVS GEN4
DESIGN:	Sid Guo	2024.07.02	P/N: SEE TABLE 1
CHECK:	Mike Chen	2024.07.02	SHEET: 3/3
APPROVAL:	Bill Lin	2024.07.02	SCALE: N/A UNIT: mm

DRAW NO. SC2007085-1

REV. A